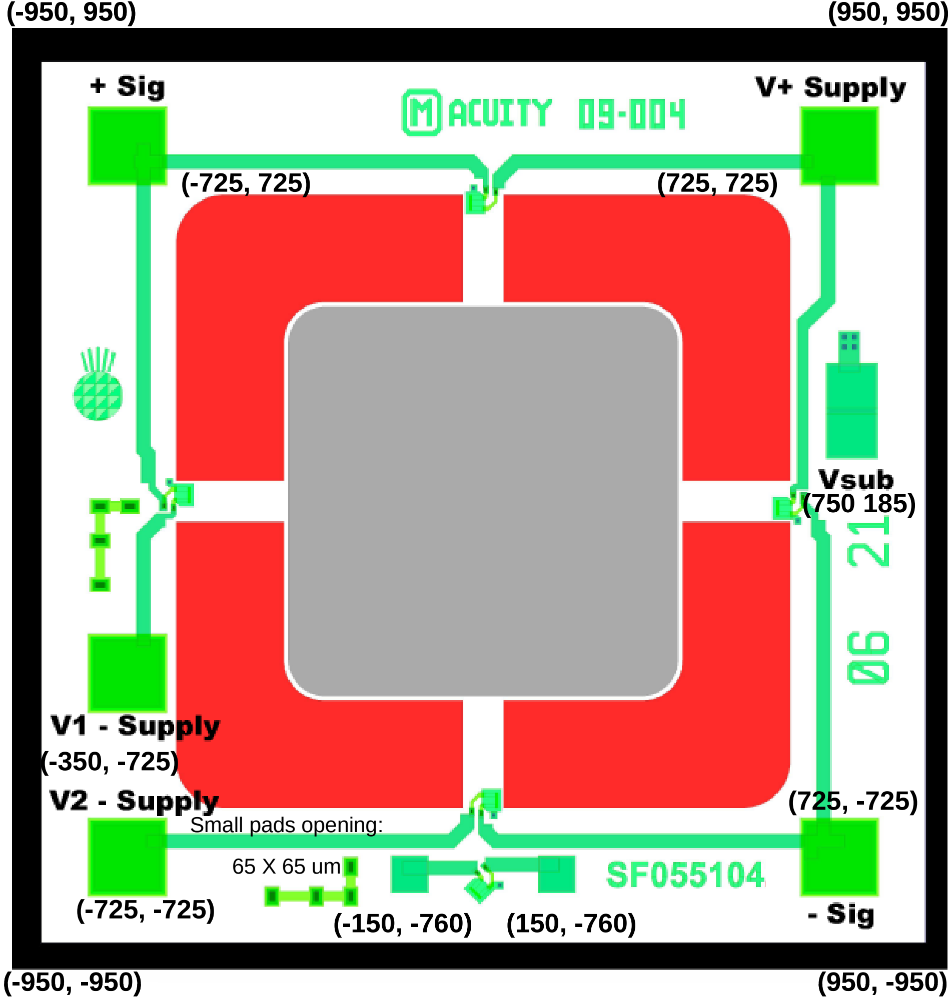
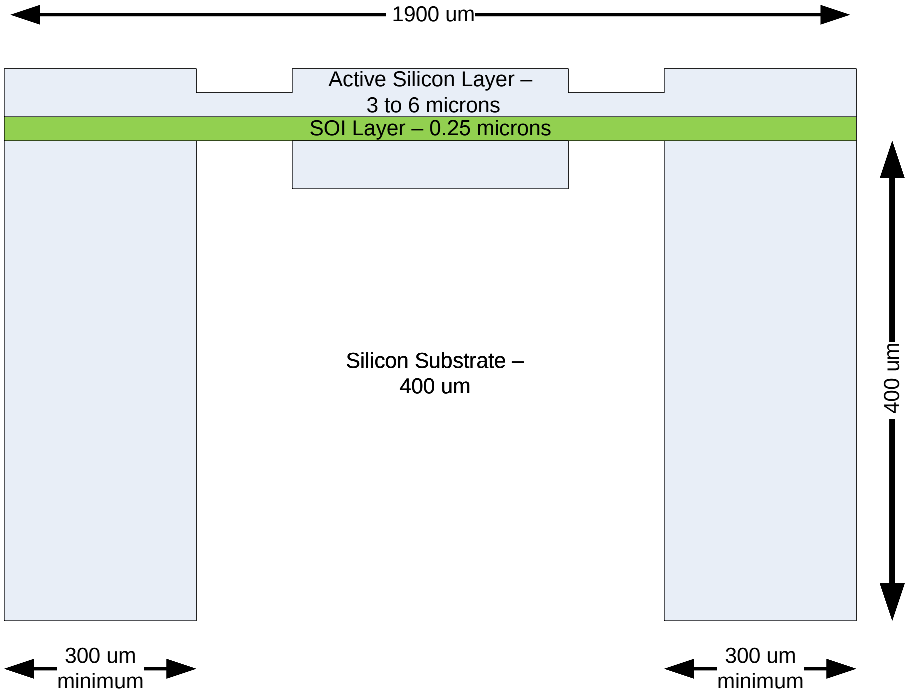
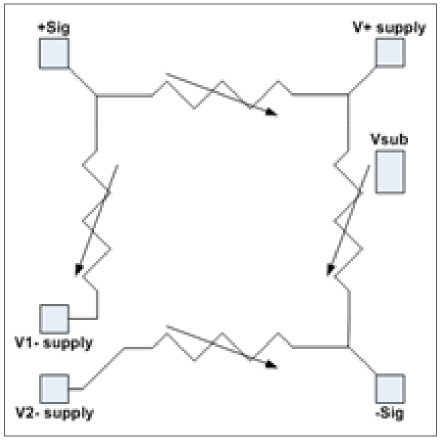
# Dimensions



NOTE:

1. All dimensions are in um.
2. The coordinates for the center of each pad, shown as (XXX,YYY), are with respect to the center of the die.
3. Pad size openings are 130 X 130 um except the substrate pad which is 90 X 180 um.
3. + Signal increases and – Signal decreases when pressure is applied from the top of the die.
4. AC3050 and AC3055 have identical bond-pad locations.
5. For maximum performance, VSub should be tied to the highest voltage in the circuit..





**Equivalent Circuit
and Pad-outs**

**Acuity Incorporated**
Fremont CA 94539 USA

www.acuitymicro.com

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|---|---|
| **Acuity Incorporated** | |
| **AC3050 Series**<br>**Dimensions and Pin-outs** | |
| Date: 8/3/2023 | By: HVAllen |
| Revision: C | |